

COPPER FILM

ABSTRACT

5 The present invention aims to provide a novel copper
coating. A copper coating, which is formed on a metal lead frame,
the copper coating comprising a particle aggregate coating having
a specific surface area of $1.3 \times 10^{-3} \text{ m}^2/\text{g}$ to $2.2 \times 10^{-3} \text{ m}^2/\text{g}$,
wherein the particle aggregate coating comprises particle
10 aggregates each having a size of $15 \text{ }\mu\text{m}$ or less.

No suitable drawings